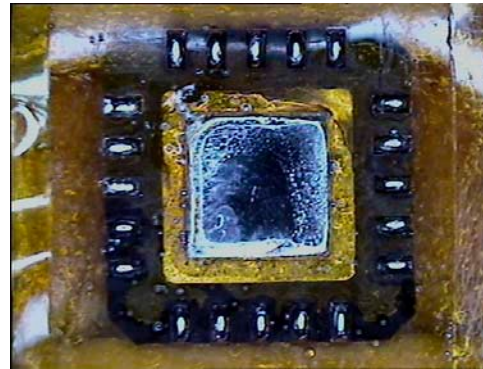
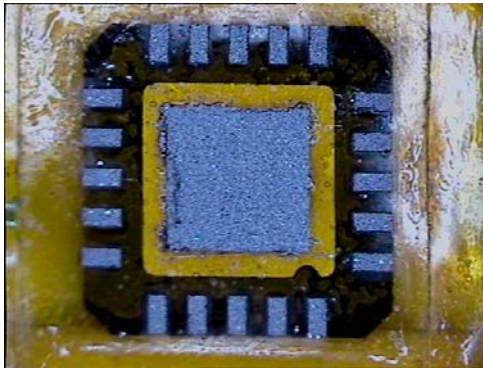


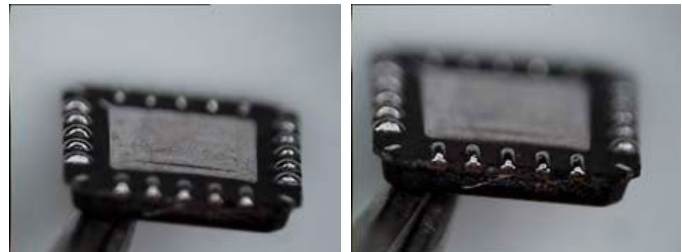
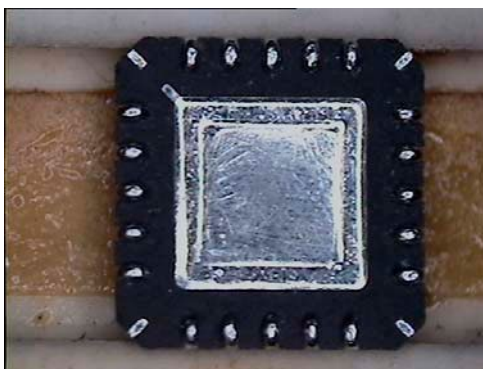
STENCILMATE™ USER INSTRUCTIONS

STEP 1
Remove device from PCB.
Wick or scavenge and clean part.



STEP 2
Place the part StencilMate™ aligning it with part lands and applying pressure to the stencil. Squeegee solder paste with a manual squeegee into the apertures. Clean off surface of stencil.

STEP 3
Reflow paste based on solder manufacturer's profile.



STEP 4
Remove StencilMate™ from device clean and inspect.

STEP 5
Inspect to make sure the "bumps" are uniform and consistent on all of the pads.